

SPECIFICATION

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1. Description

1.1 General Description

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1.2 Features

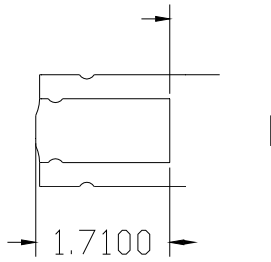
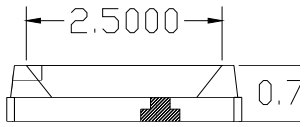
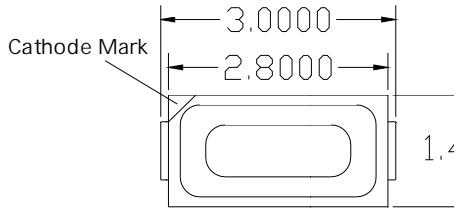
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1.3 Application

1.4 Package Dimension

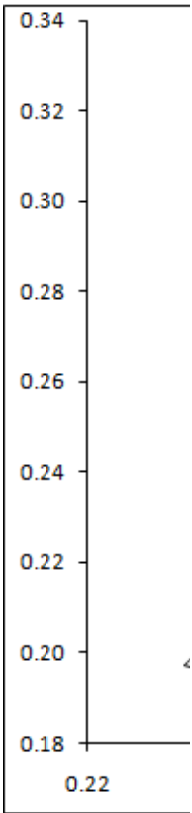


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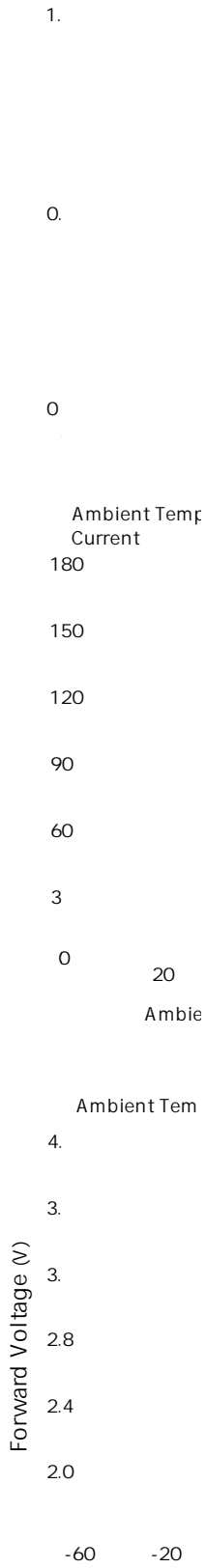
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1.5 Product Parameters

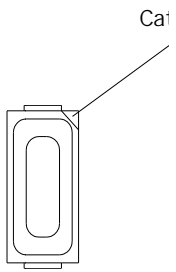
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1.7 Typical Optical



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scale 2:1



2.2 Moistur

2.3

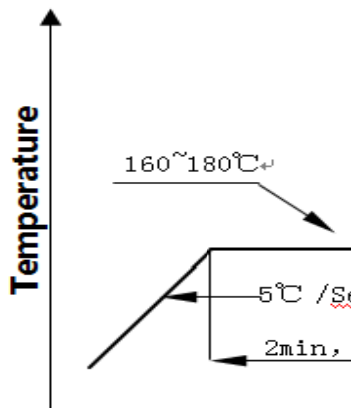
2.4 Reliability Test Items And Conditions

2.5 Criteria For Judging Damage

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3. SMT Reflow

3.1 SMT Reflow Soldering I



4. Handling Precautions

4.1 Handling Precautions



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